TI Designs

Resonant LLC Half-Bridge DC/DC Converter Software Design Guide



TI Designs

TI Designs provide the foundation that you need including methodology, testing and design files to quickly evaluate and customize and system. TI Designs help you accelerate your time to market.

Design Resources

www.ti.com/tool/TIDM-RESLLC-DCDC Hardware Design Guide

Tool Folder Containing Design Files

Hardware Design Guide

Quick Start Guide

Related Design Guide

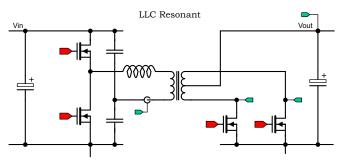
Quick Start Guide

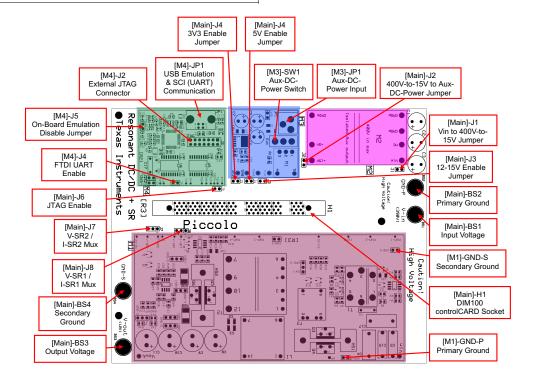
TI E2E™ Community

ASK Our E2E Experts
WEBBENCH Calculator Tools

Featured Applications

- Telecom and Server ACDC Power Supplies
- Industrial ACDC & DCDC Power Supplies
- Military Power Supplies
- EV Battery Charging







An IMPORTANT NOTICE at the end of this TI reference design addresses authorized use, intellectual property matters and other important disclaimers and information.

All trademarks are the property of their respective owners.



System Description www.ti.com

1 System Description

This guide presents a solution to control a Half-Bridge LLC Resonant DC/DC Converter with Synchronous Rectification system using TMS320F2802x microcontrollers. The Piccolo TMS320F2802x series of devices are part of the family of C2000 microcontrollers which enable cost-effective design of power supply systems. With these devices, it is possible to control power stages in an efficient and very accurate way. In addition to this, the speed of the C2000 microcontroller allows it to integrate many supplemental tasks that would, in a normal system, increase chip count and complexity. These tasks could include synchronous rectification, system management, and various communication protocols.

This guide covers how to run and get familiar with the High-Voltage Half-Bridge LLC Resonant DC/DC Converter with Synchronous Rectification Kit's HVLLC project. For an in-depth discussion of LLC Resonant DC/DC Converters and their design considerations, along with a design process example, please refer to SEM1900 Topic 3, Designing an LLC Resonant Half-Bridge Power Converter by Texas Instruments. This guide will not repeat the discussion of those details found in SEM1900 Topic 3.

2 Overview

2.1 Hardware Overview

The High-Voltage Half-Bridge LLC Resonant DC/DC Converter with Synchronous Rectification Kit power board has the following electrical specifications:

- Input voltage: 375 to 405 VDC
 Rated output power: 300 W
 Output voltage: 12 VDC
 Rated output current: 25 A
- Output voltage line regulation (lo = 1 A): ≤1%
- Output voltage load regulation (Vin = 390 V): ≤1%
- Output voltage peak-to-peak ripple (Vin = 390 V and Io = 25 A): ≤120mV
- Efficiency (Vin = 390 V and Io = 25 A): >90%
- Switching frequency (normal operation): 80 kHz to 150 kHz
- Resonant frequency: f0 = ~130 kHz



www.ti.com Overview

Figure 1 shows the LLC Resonant power stage of the board in a circuit diagram format and illustrates the major connections and feedback values being mapped to the C2000 MCU. Table 1 lists these resources. It is important to note that not all resources are available on every C2000 MCU. Please refer to the schematics and device datasheets for more detailed information.

Table 1. PWM and ADC Resource Allocation	ble 1 PV	/M and AD(C Resource	Allocation
--	----------	------------	------------	------------

Macro Name		Signal Name	PWM/ADC Channel	Description	
		PWM-1	PWM-1A	PWM-1A	Half-Bridge High-Side PWM signal
		PWM-2	PWM-1B	PWM-1B	Half-Bridge Low-Side PWM signal
		PWM-3	PWM-2A	PWM-2A	Rectifier 1 PWM signal (negative half-cycle)
	[M1]	PWM-4	PWM-3A	PWM-3A	Rectifier 2 PWM signal (positive half-cycle)
		Vo-fb	Vo-fb	ADC-A7	Output voltage sense
LLC Resonant + SR		V-SR1	V-SR1	ADC-A2	Rectifier 1 Vds voltage sense (muxed with I-SR1)
		V-SR2	V-SR2	ADC-A4	Rectifier 2 Vds voltage sense (muxed with I-SR2)
		lp-cs	lpri-cs	ADC-B1	Resonant tank current sense (rectified)
		I-SR1	I-SR1	COMP1 (ADC-A2)	Rectifier 1 current sense (muxed with V-SR1)
		I-SR2	I-SR2	COMP2 (ADC-A4)	Rectifier 2 current sense (muxed with V-SR1)

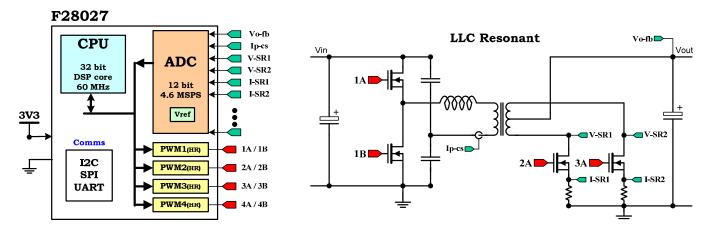


Figure 1. TMDSHVRESLLCKIT Circuit Diagram



Software Overview www.ti.com

3 Software Overview

3.1 Build Options

In order for the user to slowly build up and understand the project, the project is divided into various builds separated by #if options in the HVLLC-Main.c and HVLLC-ISR.asm files. The build used is set by the variable INCR_BUILD in HVLLC-Settings.h. Below is a short description of the different builds available in the HVLLC project.

- **Build 1** Open-Loop operation for checking functionality of the DC/DC stage
- Build 2 Closed-Loop operation of the DC/DC stage
- Build 3 Closed-Loop operation of the DC/DC stage with Analog Comparators enabled

The major variables used in the HVLLC project used to control and monitor the Half-Bridge LLC Resonant DC/DC Converter with Synchronous Rectification are listed below in Table 2 along with brief descriptions of each. The primary project files are shown in Figure 2. Digital Power Library files used are shown in Table 2.

Table 2. Major Variables

LLC_Enable	Enables the Half-Bridge PWM signals
SR_Enable	Enables the Synchronous Rectification PWM signals
Comp_Enable (Build 3 only)	Enables the Analog Comparators for current level based SR turn-off
Gui_Vset (Builds 2 and 3 only)	Sets the Closed-Loop output voltage target value (Q9)
Gui_Vout	Monitors the Output Voltage (Q9)
Pgain (Builds 2 and 3 only)	Proportional gain for PID control loop
lgain (Builds 2 and 3 only)	Integral gain for PID control loop
Dgain (Builds 2 and 3 only)	Derivative gain for PID control loop
Duty{X}	Sets the duty cycle of the PWM signals; Nominally 50%
Period	The period (1/frequency) of the PWMs. In Build 1, this is manually set by the user. In Builds 2 and 3, this is set by the control loop.
Min_Period (Builds 2 and 3 only)	Software-enforced minimum PWM period limi
Max_Period (Builds 2 and 3 only)	Software enforced maximum PWM period limit
RED	Half-Bridge PW Rising Edge Delay (high-side rising edge delay)
FED	Half-Bridge PWM Falling Edge Delay (low-side rising edge delay)
REM{X}	SR{X} PWM Rising Edge Margin (rising edge delay)
FEM{X}	SR{X} PWM Falling Edge Margin (falling edge advance)
COMP{X} (Builds 3 only)	SR{X} PWM Comparator trip value (register counts)



www.ti.com Software Overview

3.2 Primary Project Files

The key framework files used in this project are:

- **HVLLC-Main.c** This file is used to initialize, run, and manage the application. This is the "brains" behind the application.
- **HVLLC-DevInit_F2802x.c** This file is responsible for initialization and configuration of the device (in this case the F28027), and includes functions for setting up the clocks, PLL, GPIO, etc.
- **HVLLC-ISR.asm** This file contains timing critical "control type" code. This file has an initialization section that is executed one time by the C-callable assembly subroutine _DPL_Init. The file also contains the _DPL_ISR routine which executes at a rate determined by the PWM or timer used to trigger it.
- **HVLLC-Settings.h** This file is used to set global definitions for the project (ie. build options). Note that it is linked to both LED-ColorMix-Main.c and LED-ColorMix-ISR.asm.
- **HVLLC-Calculations.xls** This is a spreadsheet file that calculates the values of the various scaling factors used in converting Q-value numbers, used by the MCU, to real world values. The variables K_Vout and iK_Vset are examples of scaling factors.

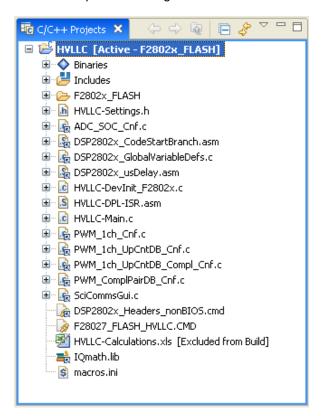


Figure 2. HVLLC Project Files



Software Overview www.ti.com

3.3 Digital Power Library Files

To reduce the effort for developing code each time, an approach of using Macro Blocks is used. These macro blocks are part of the Digital Power Library and are written in C-callable assembly and can have a C and assembly component. Following is the list of Digital Power Library files being used in this project.

Table 3. Digital Power Library Files Used

C Configuration Function	ASM Macro
ADC_SOC_Cnf.c	ADCDRV_1ch.asm
None	CNTL_2P2Z.asm
PWM_1ch_Cnf.c	None
PWM_ComplPairDB_Cnf.c	PWMDRV_LLC_ComplPairDB.asm
PWM_1ch_UpCntDB_Cnf.c	PWMDRV_LLC_1ch_UpCntDB.asm
PWM_1ch_UpCntDB_Compl_Cnf.c	PWMDRV_LLC_1ch_UpCntDB_Compl.asm

As the configuration of the peripherals is done in C, it can be easily modified. The ASM driver macro provides the necessary compact code to run in real time. For full details, please refer to the Digital Power Library documentation. The role of each file in the project is described below.

- ADC SOC Cnf.c Used to configure the ADC peripheral as specified
- **ADCDRV_1ch.asm** This macro abstracts the usage of ADC module. The driver macro copies the result from the ADCRegisters into a NetBus array variable.
- **CNTL_2P2Z.asm** This macro is a 2nd order compensator realized from an IIR filter structure. The 5 coefficients needed for this function are declared in the C background loop as an array of longs.
- PWM_1ch_Cnf.c Used to configure PWM4. PWM4 is used to trigger the control loop ISR.
- **PWM_ComplPairDB_Cnf.c** —Used to configure PWM1. PWM1 is used to control the Half-Bridge MOSFETs. PWM1 is also used to trigger the PWM update ISR.
- PWM_1ch_UpCntDB_Cnf.c Used to configure PWM3. PWM3 is used to control Synchronous Rectifier MOSFET 2.
- **PWM_1ch_UpCntDB_Compl_Cnf.c** Used to configure PWM2. PWM2 is used to control Synchronous Rectifier MOSFET 1.
- **PWMDRV_LLC_ComplPairDB.asm** Used to update PWM1 registers during operation based on user and/or control-loop inputs.
- **PWMDRV_LLC_1ch_UpCntDB.asm** Used to update PWM3 registers during operation based on user and/or control-loop inputs.
- **PWMDRV_LLC_1ch_UpCntDB_Compl.asm** Used to update PWM2 registers during operation based on user and/or control-loop inputs.

3.4 RAM and CPU Use

Table 4. RAM Memory Use of the Final Project

Build Level	Program Memory Usage 2802x	Data Memory Usage 2802x ⁽¹⁾	
Build 3 (FLASH)	220 words	499 words	

⁽¹⁾ Excluding the stack size



www.ti.com Software Overview

Table 5. CPU Usage of the Final Project

Macro Name	Number of Cycles
Control Loop ISR (100kHz)	82
Context Save, Restore, ISR Management, etc.	27
ADCDRV_1ch	6
CNTL_2P2Z	47
PWM Update ISR (100 kHz to 130 kHz)	121
Context Save, Restore, ISR management, etc.	27
PWMDRV_LLC_ComplPairDB	26
PWMDRV_LLC_1ch_UpCntDB	38
PWMDRV_LLC_1ch_UpCntDB_Compl	31
Total Number of Cycles	203
CPU Usage @ 60 Mhz (at 100 kHz)	33.83%

Table 6. System Features

Development and Emulation Code Composer Studio v4.1 (or above) with Real-Time debugging	
Target Controller	TMS320F2802x
PWM Frequency PWM1, PWM2, PWM3 – Variable 100kHz to 130 kHz. PWM4	
Interrupts Control Loop ISR – Fixed 100 kHz. Triggered by EPWM4. PWM Update ISR – Variable 100 kHz to 130 kHz. Triggered by EPWM	

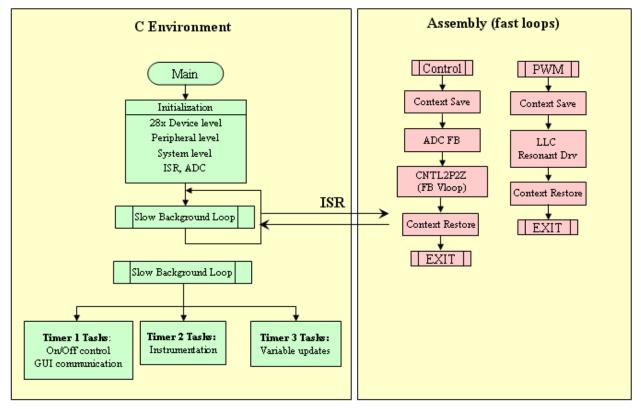


Figure 3. Software Control Flow



Software Overview www.ti.com

Hardware Setup 3.5

Figure 4 shows some of the major connectors and features of the Half-Bridge LLC Resonant DC/DC Conversion with Synchronous Rectification board. In this guide each component is named first with their macro number follow by the reference name. For example, [M2]-J1 would refer to the jumper J1 located in the macro M2 and [Main]-J1 would refer to the J1 located on the board outside of the other defined macro blocks. Refer to the Hardware Guide (literature number: TIDU256) for full details.

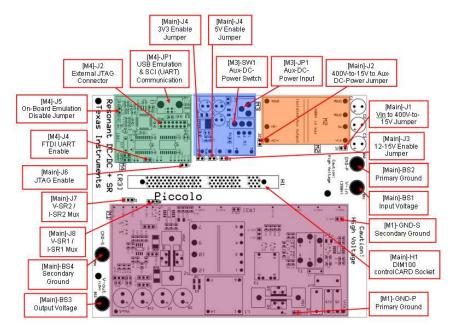


Figure 4. Hardware Features

Listed below are some of the major connectors and features of the Half-Bridge LLC Resonant DC/DC Conversion with Synchronous Rectification board. In this guide each component is named first with their macro number follow by the reference name. For example, [M2]-J1 would refer to the jumper J1 located in the macro M2 and [Main]-J1 would refer to the J1 located on the board outside of the other defined macro blocks. Refer to the Hardware Guide documentation (literature number: TIDU256) for full details.

- 1. Listed below are some of the major connectors and features of the Half-Bridge LLC Resonant DC/DC Conversion with Synchronous Rectification board. Insert a F28027 control card into socket [Main]-H1
- 2. Connect your computer to the board with a USB cable. [M4]-LD1 should turn on.
- 3. Verify the following jumper settings:
 - No jumpers are placed on [Main]-J1,J2.
 - Jumpers are placed on [Main]-J3, J4, J5,J6.
 - Jumpers are placed on pins 1-2 on [Main]-J7,J8.
 - A jumper is placed on [M4]-J4.
- 4. Connect the 12 VDC power supply to [M3]-JP1 to power the Auxiliary power rail.
- 5. Connect a 390VDC, 1A (max), power supply across [Main]-BS1, BS2.
- 6. Connect a 300W (max) load across [Main]-BS3, BS4.
- 7. Set the power switch [M3]-SW1 so that it is pointed towards the "Ext" label. [M3]-LD1 should turn on and a green LED should turn on on the controlCARD.

NOTE: If Code Composer Studio has never been installed, it may be necessary to install drivers to make the board work correctly. If a popup comes up when the USB cable is connected from the board to the computer, have the install wizard install drivers from the XDS100v1 directory of the USB drive included with this kit.



www.ti.com Software Setup

4 Software Setup

4.1 Installing Code Composer and controlSUITE

If not already installed, please install Code Composer v4.x from the USB drive included in the kit. Go to http://www.ti.com/controlsuite and run the controlSUITE installer. Select to install the "Multi-DC/DC Color LED Kit" software and allow the installer to also download all automatically checked software.

4.2 Setup Code Composer Studio to Work with the Kit

- 1. Open "Code Composer Studio v4".
- 2. Once Code Composer Studio opens, the workspace launcher may appear that would ask to select a workspace location,: (please note workspace is a location on the hard drive where all the user settings for the IDE i.e. which projects are open, what configuration is selected etc. are saved, this can be anywhere on the disk, the location mentioned below is just for reference. Also note that if this is not your first-time running Code Composer this dialog may not appear)
- 3. Click the "Browse..." button
- 4. Create the path below by making new folders as necessary
- 5. "C:\Documents and Settings\<username>\My Documents\CCSv4 workspaces\HVLLC"
- 6. Uncheck the box that says "Use this as the default and do not ask again"
- 7. Click "OK"

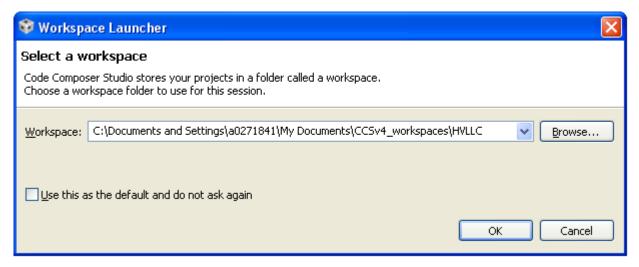


Figure 5. Workspace Launcher



Software Setup www.ti.com

8. Next we will configure Code Composer to know which MCU it will be connecting to. Click "Target -> New Target Configuration...". Name the new configuration "XDS100 F28027.ccxml". Make sure that the "Use shared location" checkbox is checked and then click "Finish".

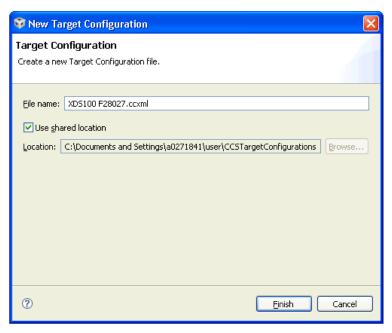


Figure 6. Creating a Target Configuration

- 9. This should open up a new tab as seen in Figure 7. Select and enter the options as shown:
 - Connection Texas Instruments XDS100v1 USB Emulator
 - Device TMS320F28027
 - Click Save
 - Close the "XDS100 F28027.ccxml" tab

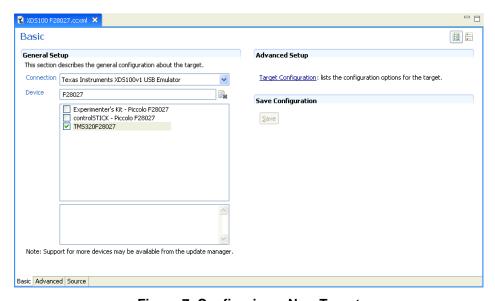


Figure 7. Configuring a New Target



www.ti.com Software Setup

10. Assuming this is your first time using Code Composer, the "XDS100 F28027" configuration is now set as the default target configuration for Code Composer. Please check this by going to "View -> Target Configurations". In the "User Defined" section, right-click on the "XDS00 F28027.ccxml" file and select "Set as Default". This tab also allows you to reuse existing target configurations and link them to specific projects.

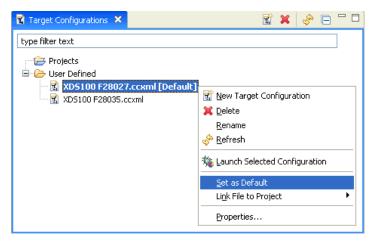


Figure 8. Setting a Default Target Configuration

- 11. Add the project into your current workspace by clicking "Project->Import Existing CCS/CCE Eclipse Project"
 - (a) Browse to the project directory within the Kit folder. The default location is: "C:\TI\controlSUITE\development_kits\TMDSHVRESLLCKIT_v1.0\HVLLC"
 - (b) Click "Finish" to load the project into the workspace.

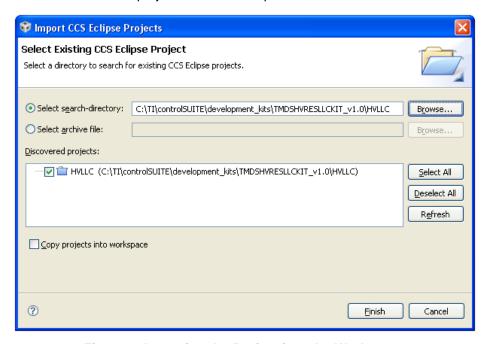


Figure 9. Importing the Project into the Workspace

12. The HVLLC project should be set as the active project. Right-click on the project name and click "Set as Active Project". Expand the file structure of the project.



Software Setup www.ti.com

4.3 Incremental System Builds

In order for the user to slowly build up and understand the project, the project is divided into various builds separated by #if options in the HVLLC-Main.c and HVLLC-ISR.asm files. The build used is set by the variable INCR_BUILD in HVLLC-Settings.h. Below is a short description of the different builds available in the HVLLC project.

- **Build 1** Open-loop operation for checking functionality of the DC/DC stage.
- **Build 2** Closed-loop operation of the DC/DC stage.
- **Build 3** Closed-loop operation of the DC/DC stage with analog comparators enabled.

4.4 Build 1: Open-Loop Operation for Checking Functionality

NOTE: Before beginning this section, ensure proper setup of the hardware and software components as described in Section 3.5 and Section 4, respectively.

The objective of this build is as follows:

- Verify that the PWM and ADC signals are working properly
- Verify that the power stage on the board is working correctly
- Manually control the period (1/frequency) of the power stage on the board and evaluate its output

The components of the system as used in the software are described in the diagram below:

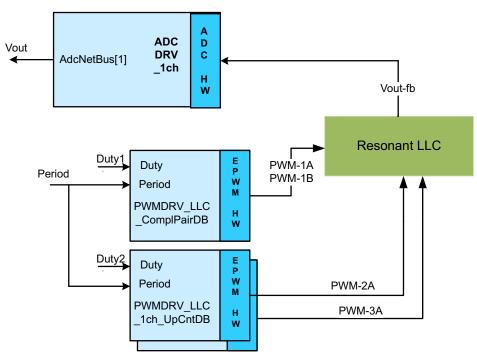


Figure 10. Build Level 1 Block Diagram

4.5 Inspect the Project

- 1. After initial boot processes are complete the software will begin from the main function. Open up HVLLC-Main.c and find the main() function (line 241).
- 2. The first thing that the software does in the main() function is call a function called DeviceInit() found in HVLLC-DevInit_F2802x.c. Open and inspect HVLLC-DevInit_F2802x.c by double clicking on the filename in the project window. In this file, the various peripheral clocks are enabled/disabled and the functional pinout, which configures which peripherals come out of which pins, is defined.



www.ti.com Software Setup

- Confirm that the ADC and PWM1-4 peripheral clocks are enabled (lines 99-117). Also confirm that GPIO00-GPIO07 are configured to be PWM outputs (lines 136-182).
- 3. The project is provided with incremental builds where different components / macro blocks of the system are pieced together one by one to form the entire system. This helps in step by step debug and understanding of the system.
 - From the C/C++ Project tab open the file HVLLC-Settings.h and make sure that INCR_BUILD is set to 1 and save this file. After we test build 1, this variable will need to be redefined to move on to build 2, and so on until all builds are complete.
- 4. Go back to the HVLLC-Main.c file and notice the various incremental build configuration code. The Build LEVEL1 configuration code is found on lines 478-493. In it, the ADC, PWM, and macro block connections are configured. Note that if INCR_BUILD is set to 1, lines 496-539 will be ignored by the compiler because they do not belong in the current build. A similar method of enabling or disabling code based on the value of INCR_BUILD is done in HVLLC-ISR.asm as well.

4.6 Build and Load the Project

- 1. Right Click on the Project Name and click on "Rebuild Project" and watch the Console window. Any errors in the project will be displayed in the Console window.
- 2. On successful completion of the build click the ** "Debug" button, located in the top-left side of the screen. The IDE will now automatically connect to the target, load the output file into the device and change to the Debug perspective.
- 3. Now click the real-time mode button that says "Enable silicon real-time mode". This will allow the user to edit and view variables in real-time without halting the program.
- 4. A message box may appear. If so, select YES to enable debug events. This will set bit 1 (DGBM bit) of status register 1 (ST1) to a "0". The DGBM is the debug enable mask bit. When the DGBM bit is set to "0", memory and register values can be passed to the host processor for updating the debugger windows.

4.7 Setup Watch Window & Graphs

Click: View -> Watch on the menu bar to open a watch window to view the variables being used in the project. Add the variables found in Figure 11 to the watch window. The format of a variable can be changed by right-clicking on a particular variable then selecting a Q-Value. Change the format of each variable to match Figure 11. The variables in this watch window are used to control and monitor the status of the board while in Build 1.

Hint: Shift-Click can be used select multiple variables or elements and then right-clicking and changing the format will affect all variables selected.



Software Setup www.ti.com

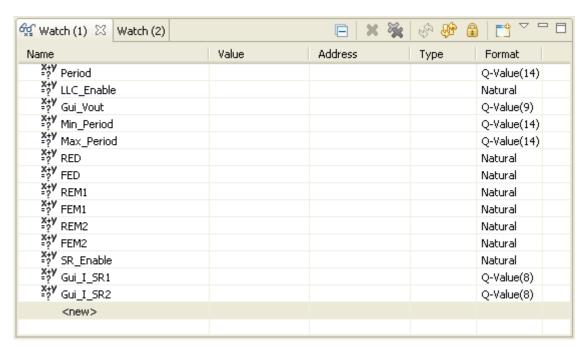


Figure 11. Configuring the Watch Window for Build 1

Click on the Continuous Refresh button in the watch window. This enables the window to run with real-time mode.

4.8 Run the Code

- 1. Run the code by pressing Run Button in the Debug Tab. The project should now run, and the values in the watch window should keep on updating.
- 2. With the primary power supply set to 0V or turned off, verify the PWM and ADC circuitry:
 - Verify that all Voltage and Current feedback variables are close to 0. They may not be exactly 0.0
 as it is normal for some low level noise to be present on the ADCs.
 - Enable the PWMs by setting "LLC_Enable" and "SR_Enable" to 1. Use an oscilloscope to verify
 the PWM waveforms. Adjust the "Period" value and verify that the frequency of the PWM
 waveforms change.
- 3. Set the load to a minimum of 1 A.
- 4. Ramp the primary power supply up to 390 VDC and verify that voltage is present on the output.
- 5. Carefully adjust "Period" and verify that "Gui_Vout" increases when you decrease "Period" and that it decreases when you increase "Period".
- 6. Carefully adjust "RED" and "FED" to see how they affect the Half-Bridge PWM signals.
- 7. Carefully adjust "REM{X}" and "FEM{X}" to see how they affect the Rectifier PWM signals.
- 8. Once complete, turn off or set the primary power supply to 0 VDC.
- 9. Disable real-time mode and Reset the processor (Target->Reset->Reset CPU) and then terminate the debug session by clicking (Target->Terminate All). This will disconnect Code Composer from the MCU.



5 Build 2: Closed-Loop Operation

The objective of this build is as follows:

Regulate the output voltage with closed-loop feedback using PID control.

The components of the system as used in the software are described in the diagram below:

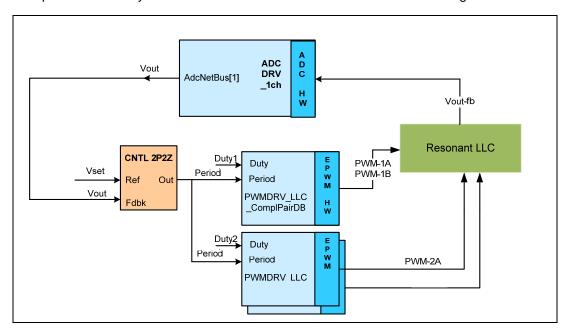


Figure 12. Build Level 2 Block Diagram

The instructions for this build will be more succinct than in the first build. Please refer to the instructions in Build 1 for further guidance. Please run build 1 prior to running build level 2.

5.1 Build and Load the Project

- Open HVLLC-Settings.h and change the incremental build level to 2 (#define INCR_BUILD 2). Save the file
- 2. Right-click on the project name and select "Rebuild Project".
- 3. On successful completion of the build click the "Debug" button, located in the top-left side of the screen. The IDE will now automatically connect to the target, load the output file into the device and change to the Debug perspective.
- 4. Now click the real-time mode button that says "Enable silicon real-time mode". This will allow the user to edit and view variables in real-time without halting the program.



5.2 Setup Watch Window and Graphs

1. Add a new watch window to the workspace and add the variables and set it to use the correct format as shown in Figure 13. The variables in this watch window are used to control and monitor the status of the board while in Build 2.

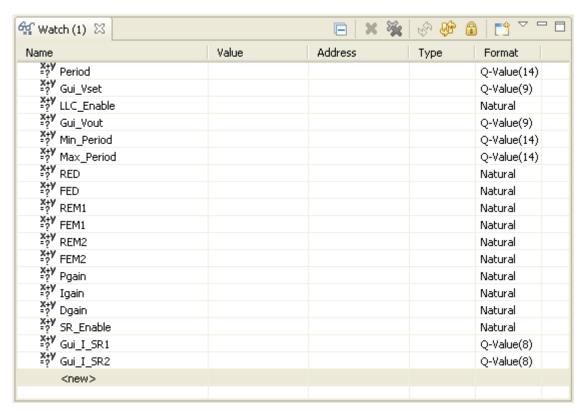


Figure 13. Configuring the Watch Window for Build 2

2. Click on the Continuous Refresh button in the watch window.

5.3 Run the Code

- 1. Run the code by pressing Run Button in the Debug Tab.
- 2. Enable the PWMs by setting "LLC_Enable" and "SR_Enable" to 1.
- 3. Set the load to a minimum of 1 A.
- 4. Ramp the primary power supply up to 390 VDC
- 5. Set "Gui_Vset" to 12 VDC. "Period" should change automatically and "Gui_Vout" should change to 12 VDC to match "Gui_Vset".
- 6. Now experiment with changing the load. Notice that "Period" (1/frequency) increases with increasing load and decreases with decreasing load.
- 7. Once complete, turn off or set the primary power supply to 0 VDC.
- 8. Disable real-time mode and Reset the processor (Target->Reset CPU) and then terminate the debug session by clicking (Target->Terminate All).



6 Build 3: Closed-Loop Operation with Analog Comparators Enabled

The objective of this build is as follows:

 Use the analog comparators to dynamically adjust the SR PWM turn-off timing based on SR current levels.

The components of the system as used in the software are described in the diagram below:

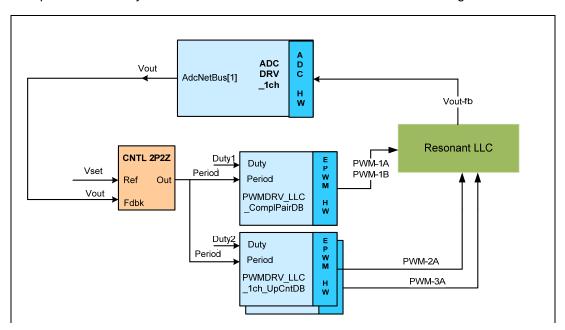


Figure 14. Build Level 3 Block Diagram

The instructions for this build will be more succinct than in the first build. Please refer to the instructions in Build 2 for further guidance. Please run build 2 prior to running build level 3.

6.1 Build and Load the Project

- Open HVLLC-Settings.h and change the incremental build level to 3 (#define INCR_BUILD 3). Save the file.
- 2. Right-click on the project name and select "Rebuild Project".
- 3. On successful completion of the build click the "Debug" button, located in the top-left side of the screen. The IDE will now automatically connect to the target, load the output file into the device and change to the Debug perspective.
- 4. Now click the real-time mode button that says "Enable silicon real-time mode". This will allow the user to edit and view variables in real-time without halting the program.

6.2 Setup Watch Window and Graphs

Add a new watch window to the workspace and add the variables and set it to use the correct format as shown in Figure 15. The variables in this watch window are used to control and monitor the status of the board while in Build 3.



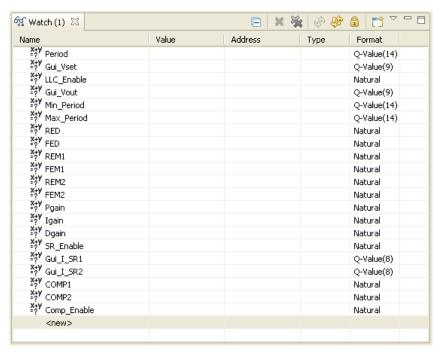


Figure 15. Configuring the Watch Window for Build 3

1. Click on the Continuous Refresh button in the watch window.

6.3 Run the Code

- 1. Run the code by pressing Run Button in the Debug Tab.
- 2. Enable the PWMs by setting "LLC_Enable" and "SR_Enable" to 1.
- 3. Use an oscilloscope to probe the SR PWM and SR Current signals.
- 4. Set the load to a minimum of 1 A.
- 5. Ramp the primary power supply up to 390 VDC
- 6. Set "Gui Vset" to 12 VDC.
- 7. Set the load to 10 A.
- 8. On the oscilloscope, make a note of where the SR PWM signal's falling edge is relative to where the SR Current drops back to 0.
- 9. Set "Comp_Enable" to 1. Observe how the SR PWM signal's falling edge has shifted. The SR PWM signal's falling edge should now be closer to where the SR Current drops back to 0.
- 10. Now experiment with changing the load. Notice that the SR PWM signal's falling edge tracks where the SR Current drops back to 0.
- 11. Now experiment with changing the "COMP{X}" value. This affects the current level at which the analog comparator will allow the SR PWM to turn-off.
- 12. Once complete, turn off or set the primary power supply to 0 VDC.
- 13. Disable real-time mode and Reset the processor (Target->Reset CPU) and then terminate the debug session by clicking (Target->Terminate All).

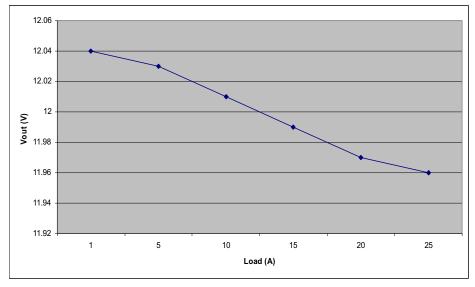
NOTE: The analog comparators is used to delay the SR PWM's falling edge and will not advance the falling edge beyond that specified by "FEM{X}".



www.ti.com Test Results

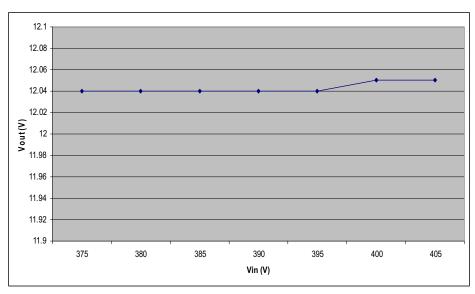
7 Test Results

This section contains various experimental results for use as references while experimenting with the High-Voltage Half-Bridge LLC Resonant DC/DC Converter Kit.



(1) Vin = 390 VDC

Figure 16. Output Voltage: Load Regulation

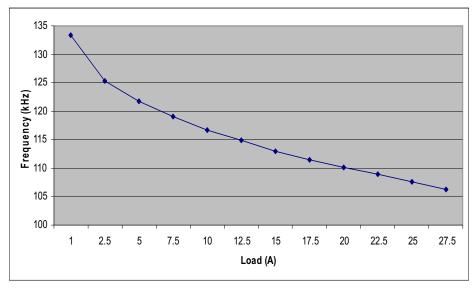


(1) lo = 1 A

Figure 17. Output Voltage: Line Regulation

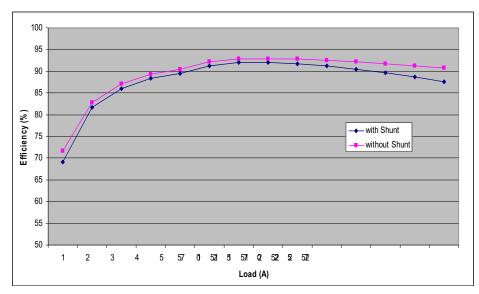


Test Results www.ti.com



(1) Vin = 390 VDC

Figure 18. Switching Frequency vs Load

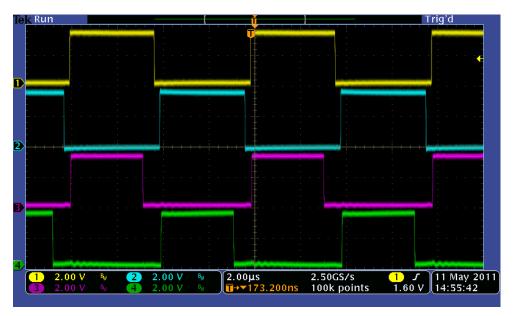


(1) Vin = 390 VDC

Figure 19. Efficiency vs Load

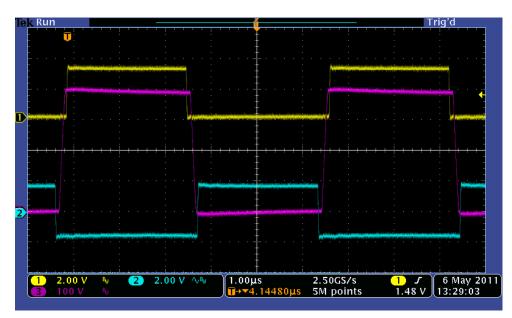


www.ti.com Test Results



- (1) Yellow HB HS
- (2) Blue HB LS
- (3) Purple SR2
- (4) Green SR1

Figure 20. PWM Timings Example

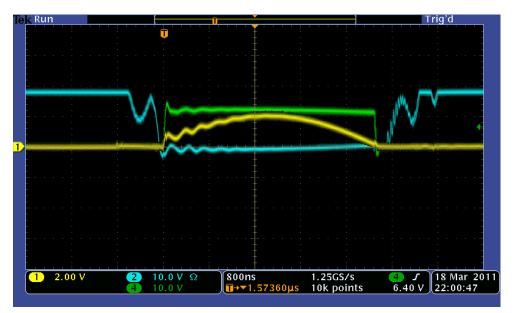


- (1) Yellow HB HS PWM
- (2) Blue HB LS PWM
- (3) Purple MP Voltage

Figure 21. Half-Bridge Zero Voltage Switching

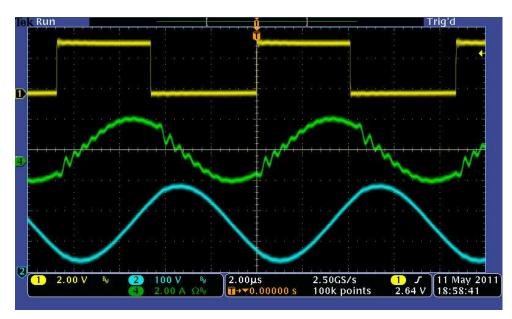


Test Results www.ti.com



- (1) Yellow SR Current
- (2) Blue SR Mosfet Vds
- (3) Green SR PWM

Figure 22. Rectifier Zero Current Switching

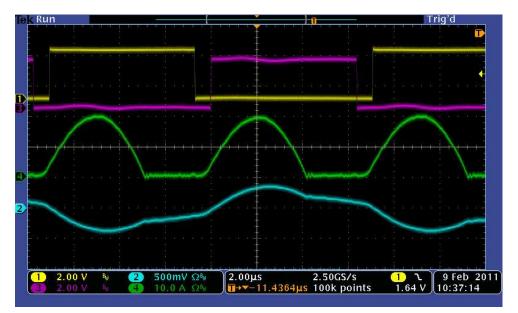


- (1) Yellow HB HS PWM
- (2) Green Tank Current
- (3) Blue Capacitor Voltage

Figure 23. Resonant Tank Operational Waveforms



www.ti.com Test Results



- (1) Yellow HB HS PWM
- (2) Purple HB LS PWM
- (3) Green Combined SR Currents
- (4) Blue Tank Current

Figure 24. Operational Current Waveforms



- (1) Blue Output Voltage
- (2) Green Load Current
- A Transient results taken using 2P2Z coefficients and 2790 uF output capacitance

Figure 25. Transient Response: 10% ↔ 60% load steps

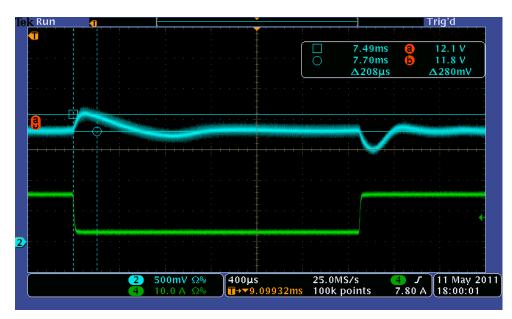


Test Results www.ti.com



- (1) Blue Output Voltage
- (2) Green Load Current
- A Transient results taken using 2P2Z coefficients and 2790 uF output capacitance

Figure 26. Transient Response: 10% → 60% load step

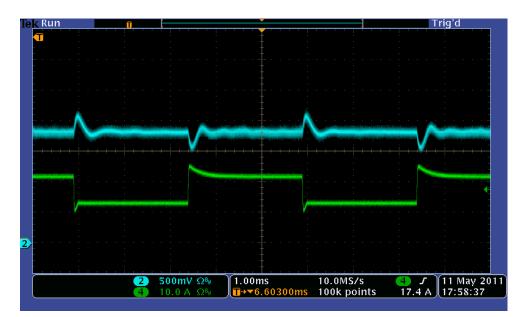


- (1) Blue Output Voltage
- (2) Green Load Current
- A Transient results taken using 2P2Z coefficients and 2790 uF output capacitance

Figure 27. Transient Response: 60% → 10% load step

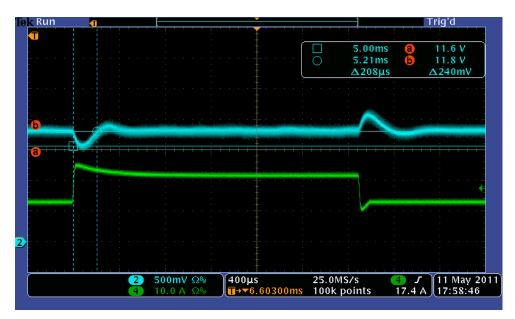


www.ti.com Test Results



- (1) Blue Output Voltage
- (2) Green Load Current
- A Transient results taken using 2P2Z coefficients and 2790 uF output capacitance

Figure 28. Transient Response: 50% ↔ 100% load steps



- (1) Blue Output Voltage
- (2) Green Load Current
- A Transient results taken using 2P2Z coefficients and 2790 uF output capacitance

Figure 29. Transient Response: 50% → 100% load step

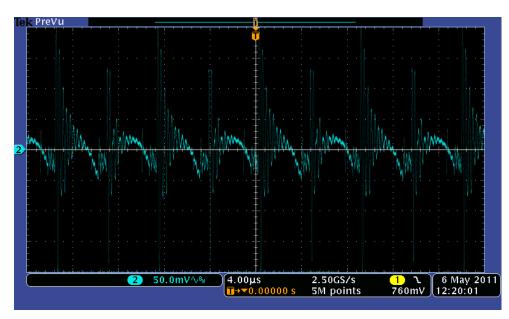


Test Results www.ti.com



- (1) Blue Output Voltage
- (2) Green Load Current
- A Transient results taken using 2P2Z coefficients and 2790 uF output capacitance

Figure 30. Transient Response: 100% \rightarrow 50% load step



(1) Blue - Output Voltage

Figure 31. High Frequency Voltage Ripple



www.ti.com References

8 References

For additional information, please refer to the following:

HVLLC-SWGuide — Provides detailed information on the CCS4 project.

\TMDSHVRESLLCKIT_v1.0\~Docs\ HVLLC-SWGuide[R3].pdf

HVLLC-HWGuide — Provides detailed information on the hardware on the board.

\TMDSHVRESLLCKIT_v1.0\~Docs\ HVLLC-HWGuide[R3].pdf

HVLLC-HWdevPkg — A folder containing files related to the hardware on the board (schematics, bill of materials, Gerber files, PCB layout, etc).

\TMDSHVRESLLCKIT_v1.0\~HVLLC-HWdevPkg[R3]\

IMPORTANT NOTICE FOR TI REFERENCE DESIGNS

Texas Instruments Incorporated ("TI") reference designs are solely intended to assist designers ("Buyers") who are developing systems that incorporate TI semiconductor products (also referred to herein as "components"). Buyer understands and agrees that Buyer remains responsible for using its independent analysis, evaluation and judgment in designing Buyer's systems and products.

TI reference designs have been created using standard laboratory conditions and engineering practices. TI has not conducted any testing other than that specifically described in the published documentation for a particular reference design. TI may make corrections, enhancements, improvements and other changes to its reference designs.

Buyers are authorized to use TI reference designs with the TI component(s) identified in each particular reference design and to modify the reference design in the development of their end products. HOWEVER, NO OTHER LICENSE, EXPRESS OR IMPLIED, BY ESTOPPEL OR OTHERWISE TO ANY OTHER TI INTELLECTUAL PROPERTY RIGHT, AND NO LICENSE TO ANY THIRD PARTY TECHNOLOGY OR INTELLECTUAL PROPERTY RIGHT, IS GRANTED HEREIN, including but not limited to any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services, or a warranty or endorsement thereof. Use of such information may require a license from a third party, or a license from TI under the patents or other intellectual property of TI.

TI REFERENCE DESIGNS ARE PROVIDED "AS IS". TI MAKES NO WARRANTIES OR REPRESENTATIONS WITH REGARD TO THE REFERENCE DESIGNS OR USE OF THE REFERENCE DESIGNS, EXPRESS, IMPLIED OR STATUTORY, INCLUDING ACCURACY OR COMPLETENESS. TI DISCLAIMS ANY WARRANTY OF TITLE AND ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE, QUIET ENJOYMENT, QUIET POSSESSION, AND NON-INFRINGEMENT OF ANY THIRD PARTY INTELLECTUAL PROPERTY RIGHTS WITH REGARD TO TI REFERENCE DESIGNS OR USE THEREOF. TI SHALL NOT BE LIABLE FOR AND SHALL NOT DEFEND OR INDEMNIFY BUYERS AGAINST ANY THIRD PARTY INFRINGEMENT CLAIM THAT RELATES TO OR IS BASED ON A COMBINATION OF COMPONENTS PROVIDED IN A TI REFERENCE DESIGN. IN NO EVENT SHALL TI BE LIABLE FOR ANY ACTUAL, SPECIAL, INCIDENTAL, CONSEQUENTIAL OR INDIRECT DAMAGES, HOWEVER CAUSED, ON ANY THEORY OF LIABILITY AND WHETHER OR NOT TI HAS BEEN ADVISED OF THE POSSIBILITY OF SUCH DAMAGES, ARISING IN ANY WAY OUT OF TI REFERENCE DESIGNS OR BUYER'S USE OF TI REFERENCE DESIGNS.

TI reserves the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques for TI components are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

Reproduction of significant portions of TI information in TI data books, data sheets or reference designs is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards that anticipate dangerous failures, monitor failures and their consequences, lessen the likelihood of dangerous failures and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in Buyer's safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed an agreement specifically governing such use.

Only those TI components that TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components that have *not* been so designated is solely at Buyer's risk, and Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.